

# DE2S068

## Silicon epitaxial planar type

For ESD protection

### ■ Features

- High electrostatic discharge ESD
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### ■ Packaging

Embossed type (Thermo-compression sealing): 10000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Total power dissipation *1	$P_T$	150	mW
Electrostatic discharge *2	ESD	$\pm 30$	kV
Junction temperature	$T_j$	150	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$

Note) \*1:  $P_T = 150$  mW achieved with a printed circuit board.

\*2: Test method: IEC61000-4-2 (C = 150 pF, R = 330  $\Omega$ , Contact discharge: 10 times)

### ■ Package

- Code  
SSMini2-F5-B
- Pin Name
  1. Cathode
  2. Anode

### ■ Marking Symbol: E2

### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

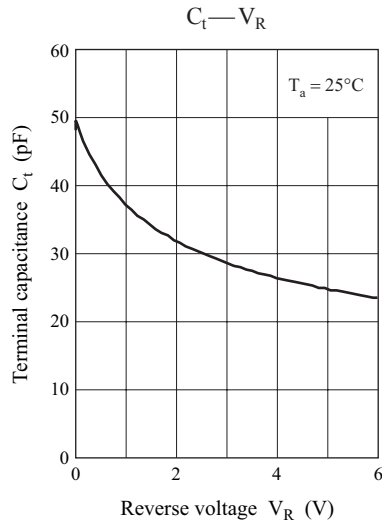
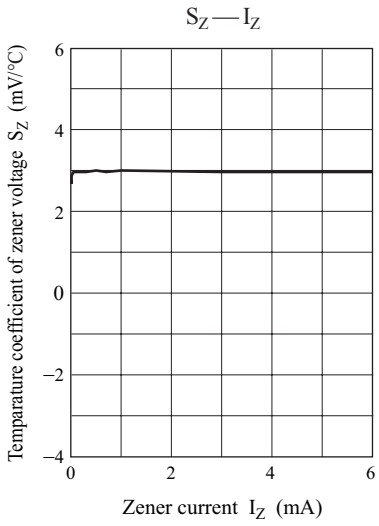
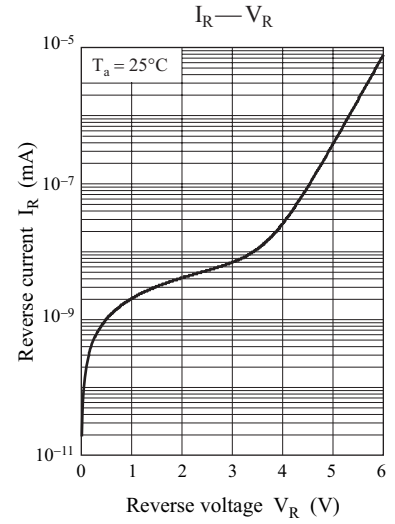
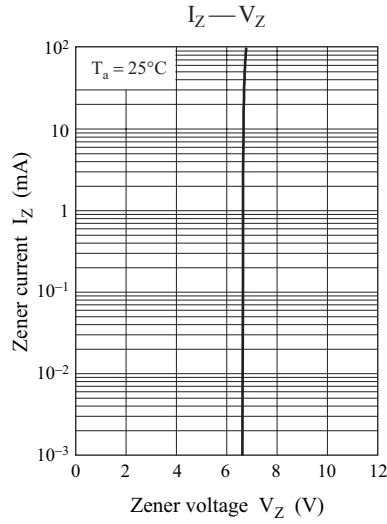
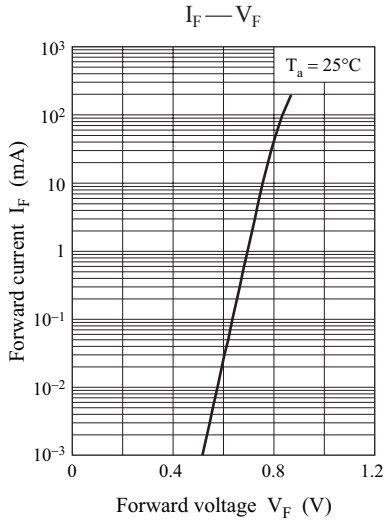
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage *1,2	$V_Z$	$I_R = 1$ mA	6.46		7.14	V
Reverse current	$I_R$	$V_R = 4$ V			0.5	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		50		pF
Temperature coefficient of zener voltage *3	$S_Z$	$I_Z = 1$ mA		3.0		mV/ $^\circ\text{C}$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. \*1: The temperature must be controlled  $25^\circ\text{C}$  for  $V_Z$  measurement.  $V_Z$  value measured at other temperature must be adjusted to  $V_Z (25^\circ\text{C})$

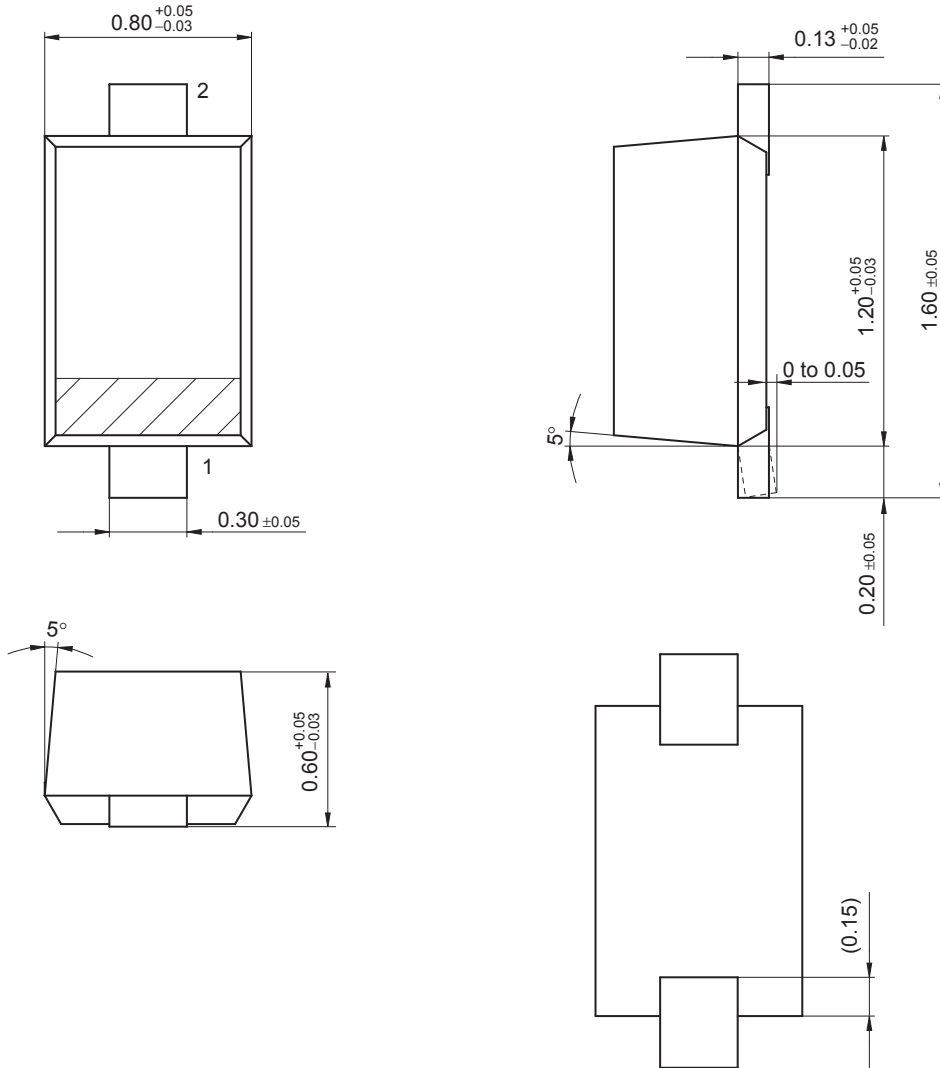
\*2:  $V_Z$  guaranteed 20 ms after current flow.

\*3:  $T_j = 25^\circ\text{C}$  to  $150^\circ\text{C}$



SSMini2-F5-B

Unit: mm



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